

Sixth Semester B.E. Degree Examination, Dec.2019/Jan.2020 Micro and Smart Systems Technology

Time: 3 hrs.

Max. Marks:100

Note: Answer any FIVE full questions, selecting at least TWO questions from each part.

		PART – A	
1	a.	Discuss the Evaluation of Micro-fabrication and smart material.	(10 Marks)
	b.	In detail highlight the applications of microsystems.	(10 Marks)
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2	a.	With a neat diagram, discuss the principle of operation of silicon capacitive acce	elerometer.
			(10 Marks)
	b.	Discuss the working of piezo-resistive pressure sensor and its applications.	(10 Marks)
3	a.	With a neat diagram, explain the process of photolithography.	(10 Marks)
	b.	Differentiate between Wet and Dry etching methods used in microtechnology.	(05 Marks)
	C.	Write a short note on Thick – film processing.	(05 Marks)
4	a.	Discuss the detail scaling of magnetic forces and electro static forces.	(10 Marks)
7	b.	Explain the scaling issues while modeling the micro systems.	(10 Marks)
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		PART – B	
5	a.	Explain the Finite element method in detail.	(10 Marks)
	b.	With neat diagram and necessary equation illustrate the actuation effect in a pi	
		plate.	(10 Marks)
6	a.	Explain switched capacitor circuits for capacitance measurement.	(10 Marks)
Ü	b.	With a neat diagram, explain the characteristics of Instrumentation amplifiers.	(10 Marks)
7	a.	Explain the issues in microsystem packaging.	(10 Marks)
	b.	Discuss the following packaging Technologies	
		i) Ball grid array ii) Wire bonding.	(10 Marks)
8	a.	Explain the working of a piezo resistive pressure sensor and define the terms sensor	sitivity and
3		offset voltage. Draw the diagram at necessary places.	(10 Marks)
	b.	Explain the micro-machined accelerometer with neat diagram.	(06 Marks)
	c.	Draw the circuit diagram of MOSFET integrated pressure sensor. Explain the open	
			(04 Marks)

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